

10 9 8 7 6 5 4 3 2 1

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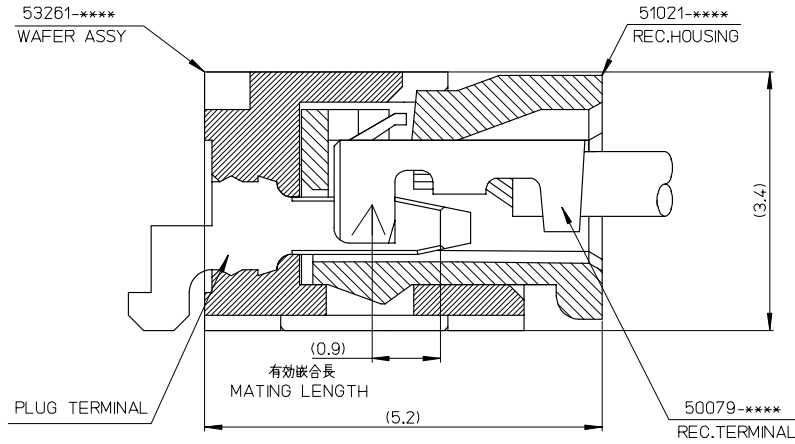
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53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI CHKD: YMAEDA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-T-O-B CONN. 51021,53261 MATING CROSS SECTION		
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002		
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1		
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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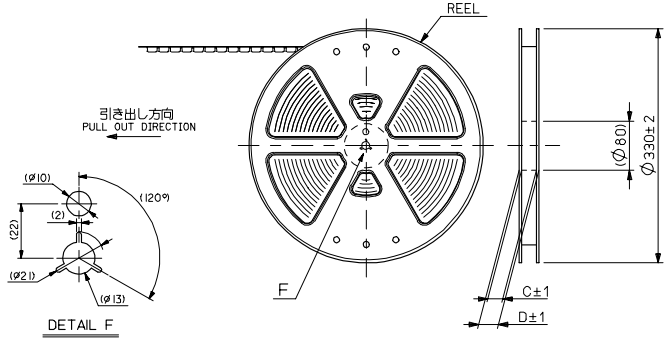
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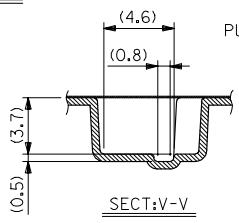
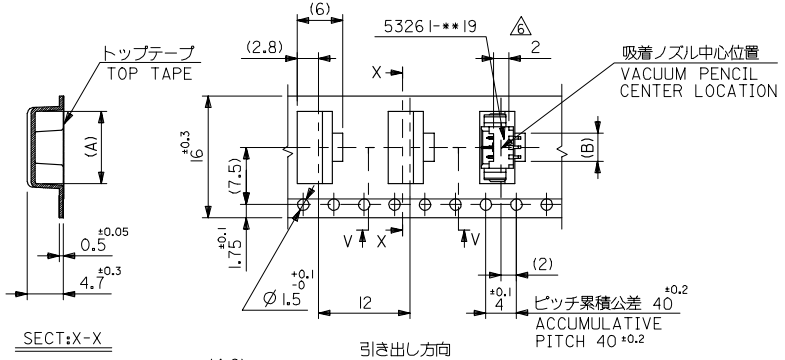
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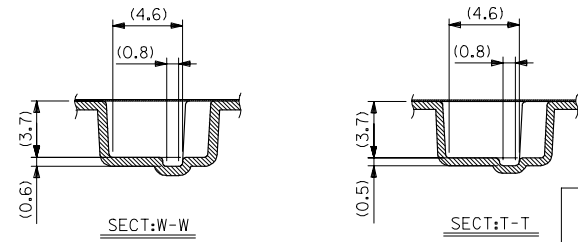
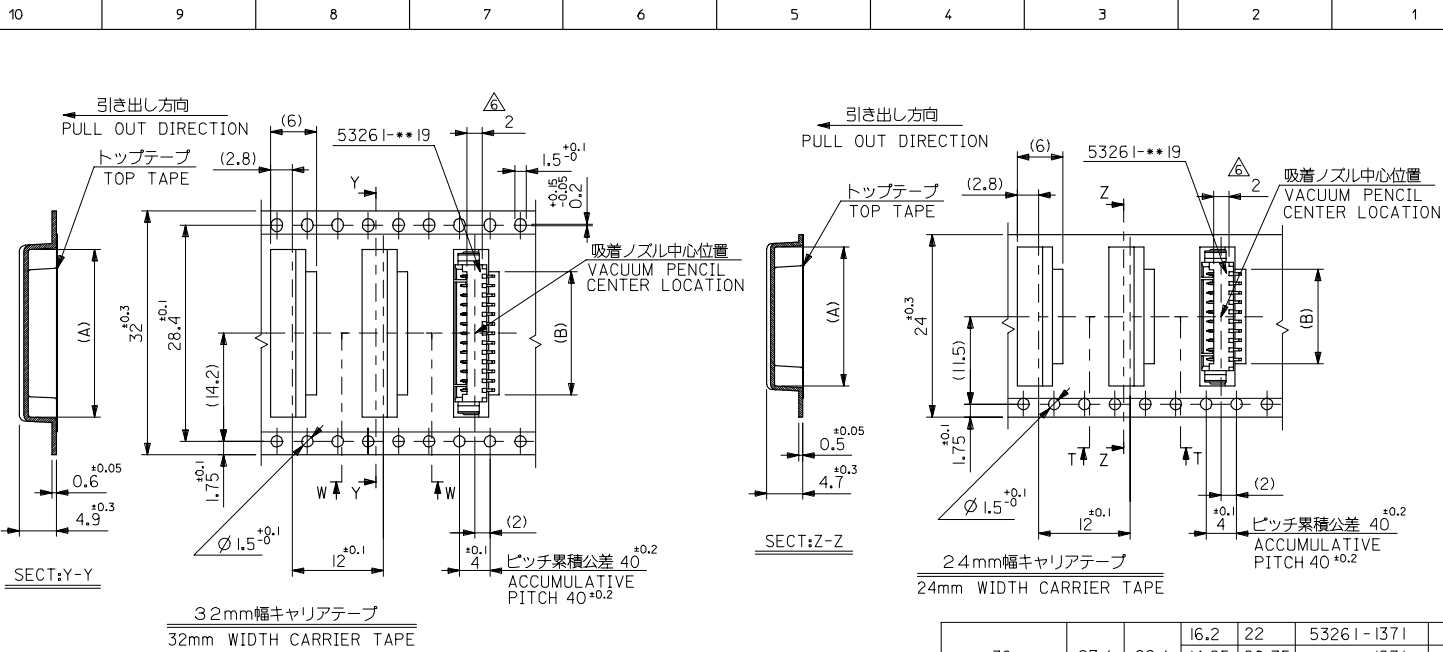
- 注記 NOTES**
- 53261-***19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
 - 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
 - リードテープ長さ LEAD TAPE LENGTH
トップテープリーダ部 TOP TAPE LEADER PART 175 *25
トップテープ未接着部 TOP TAPE NON-BONDED PART 25 *5
 - 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (P.S) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>



16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

- コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA
- 本製品は 53261-***90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-***90
- ELV及びRoHS適合品
ELV AND ROHS COMPLIANT

MODEL NO.	53261-***71	キャリアテープ幅 CARRIER TAPE WIDTH	16	21.4	17.4	3.7	9.5	53261-0371	3	
GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY		D	C	B	A	MATERIAL. NO.	種数 CKT.	53261-0271	2
10 UNDER ±0.2	SCALE ---		---	---	---	---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	
10 OVER 30 UNDER ±0.25	DRAWN BY H.SHIMABUKUR		DATE '04/02/06		CHECKED BY K.TOJO		DATE '04/02/06		APPROVED BY M.SASAO	
30 OVER ±0.3	APPROVED BY M.SASAO		DATE '04/02/06		MATERIAL NO.		DOCUMENT NO. SD-53261-023		SHEET NO. 1 OF 3	
ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MATERIAL NO.		DOCUMENT NO. SD-53261-023		SHEET NO. 1 OF 3	
REVISED		DESCRIPTION		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



32	37.4	33.4	16.2	22	53261-1371	I3
24	29.4	25.4	14.95	20.75	-1271	I2
			13.7	19.5	-1171	II
			12.45	18.25	-1071	IO
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
4.95	10.75	53261-0471	4			

MODEL NO.	53261-xx71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
10 UNDER	±0.2	DRAWN BY H.SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO		DATE '04/02/06		MOLEX INCORPORATED		
30 OVER	±0.3	APPROVED BY M.SASAO		DATE '04/02/06				
ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53261-023		2 OF 3		
REVISED		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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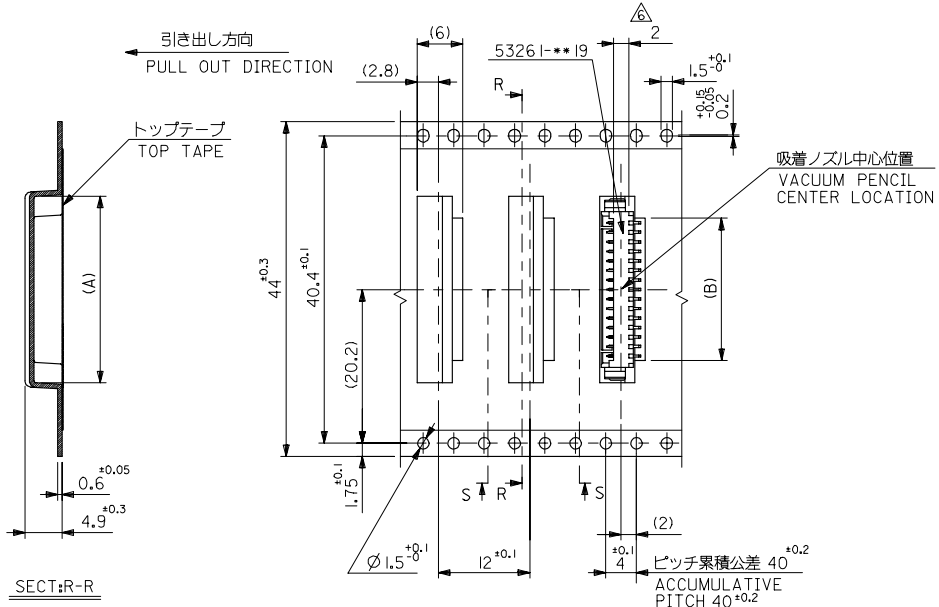
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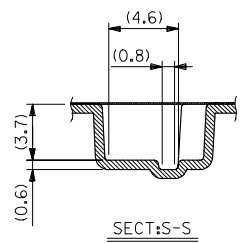
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SECT:R-R



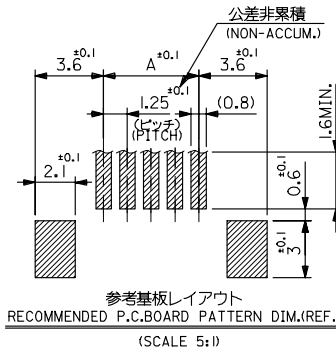
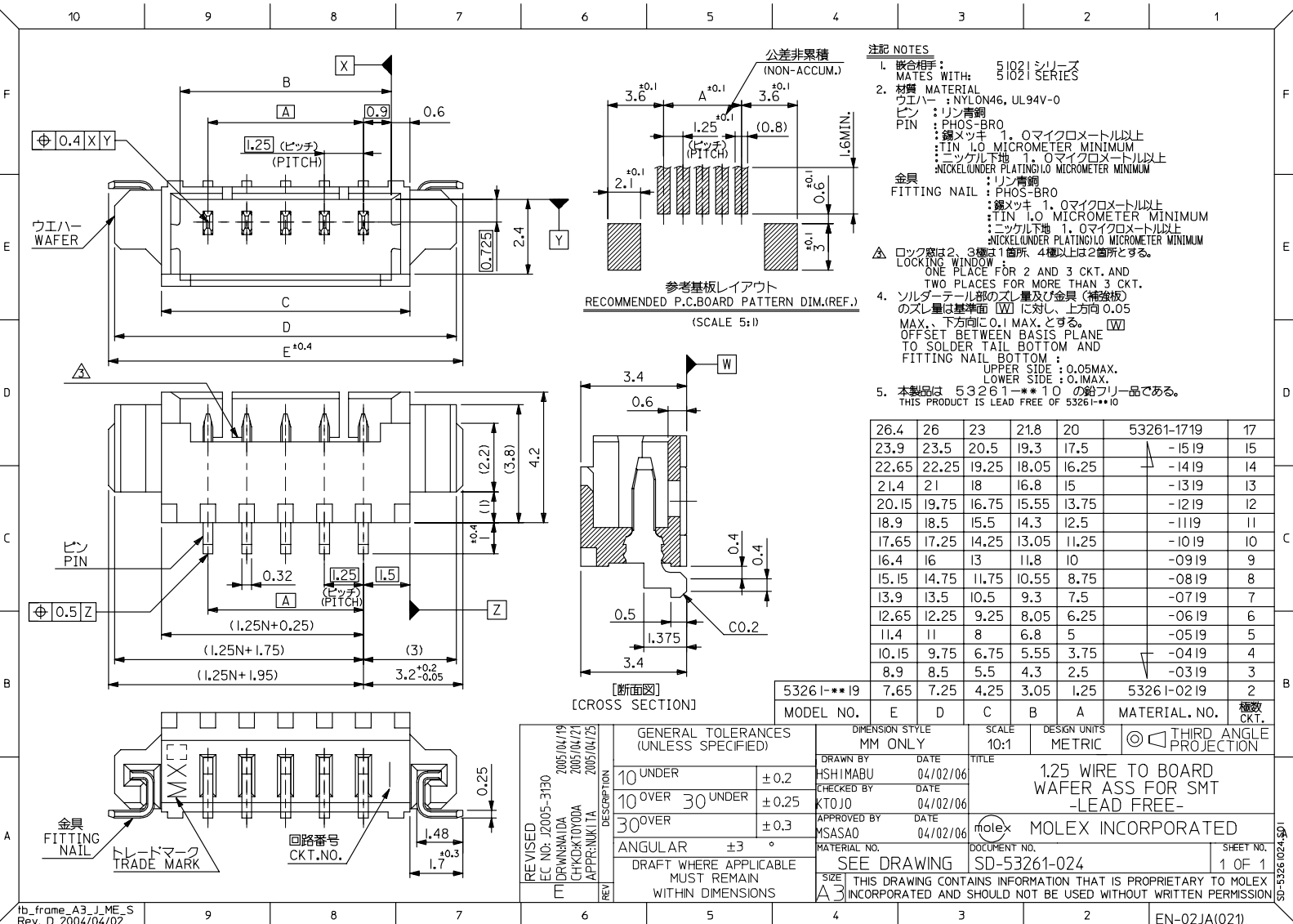
SECT:S-S

4.4mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

MODEL NO. 53261-x*71		44	49.4	45.4	18.7	24.5	53261-I571	I5
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	53261-I471	I4	極数 CKT.
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
10 UNDER	±0.2	DRAWN BY H.SHIMABUKUR		DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO		DATE '04/02/06	MATERIAL NO. 53261-I471			
30 OVER	±0.3	APPROVED BY M.SASAO		DATE '04/02/06	MATERIAL NO. 53261-I571			
ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.	MATERIAL NO. 53261-I471			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MATERIAL NO. 53261-I471		DOCUMENT NO. SD-53261-023		
REVISED		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				SHEET NO. 3 OF 3

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注記 NOTES

- 嵌合相手: 51021 シリーズ
 MATES WITH: 51021 SERIES
- 材質 MATERIAL: NYLON46, UL94V-0
 PIN: リン青銅
 : PHOS-BRO
 : 鍍メッキ 1. 0マイクromメートル以上
 : TIN 1.0 MICROMETER MINIMUM
 : ニッケル下地 1. 0マイクromメートル以上
 : NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM
 金具 FITTING NAIL: リン青銅
 : PHOS-BRO
 : 鍍メッキ 1. 0マイクromメートル以上
 : TIN 1.0 MICROMETER MINIMUM
 : ニッケル下地 1. 0マイクromメートル以上
 : NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM
- ロック窓は2, 3個は1箇所、4個以上は2箇所とする。
 LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
- ソルダーテール部のスリ量及び金具(補強材)のスリ量は基準面 [W] に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。 [W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
 UPPER SIDE: 0.05MAX.
 LOWER SIDE: 0.1MAX.
- 本製品は 53261-**-**10 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 53261-**-**10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
53261-**-**19	7.65	7.25	4.25	3.05	1.25	53261-0219	2

REVISED EC NO. J2005-3130 DRAWN BY CHKD BY APPR. NIKITA 2005/04/19 2005/04/21 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024		
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE DRAWING	SHEET NO. 1 OF 1		
SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			